

### MiniSKiiP<sup>®</sup> 0

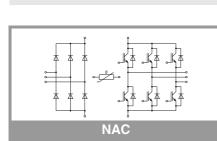
#### SKiiP 03NAC12T4V1

#### Features\*

- Trench 4 IGBTs
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

#### Remarks

- Max. case temperature limited to  $T_{C}{=}125^{\circ}C$
- Product reliability results valid for  $T_j \le 150^{\circ}C$  (recommended  $T_{j,op} = -40...+150^{\circ}C$ )
- Temperature sensor: No basic insulation to main circuit, max. potential difference 850V to -DC



Absolute	Maximum Ratin	gs			
Symbol	Conditions		Values		
Inverter -	IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1200	V	
Ic	T <sub>i</sub> = 150 °C	T <sub>s</sub> = 25 °C	7.5	А	
	$T_j = 150 \text{ C}$	T <sub>s</sub> = 70 °C	7.5	А	
I <sub>C</sub>	T <sub>i</sub> = 175 °C	T <sub>s</sub> = 25 °C	7.5	А	
	$= 1_j = 175$ C	T <sub>s</sub> = 70 °C	7.5	А	
I <sub>Cnom</sub>			8	А	
I <sub>CRM</sub>			24	А	
V <sub>GES</sub>			-20 20	V	
	V <sub>CC</sub> = 800 V				
t <sub>psc</sub>	V <sub>GE</sub> ≤ 15 V V <sub>CES</sub> ≤ 1200 V	T <sub>j</sub> = 150 °C	10	μs	
Tj			-40 175	°C	
Inverse -	Diode				
V <sub>RRM</sub>	T <sub>i</sub> = 25 °C		1200	V	
l <sub>F</sub>	T 150 °C	T <sub>s</sub> = 25 °C	9	Α	
$T_j = 150 \text{ °C}$	$= 1_j = 150$ C	T <sub>s</sub> = 70 °C	9	Α	
l <sub>F</sub>	T <sub>i</sub> = 175 °C	T <sub>s</sub> = 25 °C	9	А	
	$= 1_j = 175$ C	T <sub>s</sub> = 70 °C	9	Α	
I <sub>FRM</sub>			24	Α	
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180°, T <sub>j</sub> = 150 °C		36	Α	
Tj			-40 175		
Rectifier ·	- Diode				
V <sub>RRM</sub>	T <sub>i</sub> = 25 °C		1600	V	
l <sub>F</sub>	T <sub>s</sub> = 25 °C, T <sub>j</sub> = 1	50 °C	39		
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	220	Α	
	sin 180°	T <sub>j</sub> = 150 °C	200	Α	
i²t	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	242	A <sup>2</sup> s	
	sin 180°	T <sub>j</sub> = 150 °C	200	A <sup>2</sup> s	
Tj			-40 150	°C	
Module					
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 80 °C, 2	20 A per spring	t.b.d.	А	
T <sub>stg</sub>	module without T	ГIМ	-40 125	°C	
V <sub>isol</sub>	AC sinus 50 Hz,	1 min	2500		

Characteristics								
Symbol	Conditions	min.	typ.	max.	Unit			
Inverter - IGBT								
V <sub>CE(sat)</sub>	I <sub>C</sub> = 8 A V <sub>GE</sub> = 15 V chiplevel	T <sub>j</sub> = 25 °C		1.85	2.10	V		
		T <sub>j</sub> = 150 °C		2.25	2.45	V		
V <sub>CE0</sub>	chiplevel	T <sub>j</sub> = 25 °C		0.80	0.90	V		
	chiplevel	T <sub>j</sub> = 150 °C		0.70	0.80	V		
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25 °C		131	150	mΩ		
	chiplevel	T <sub>j</sub> = 150 °C		194	206	mΩ		
V <sub>GE(th)</sub>	$V_{GE} = V_{CE} V, I_C = 1 \text{ mA}$		5	5.8	6.5	V		
I <sub>CES</sub>	ces V <sub>GE</sub> = 0 V	T <sub>j</sub> = 25 °C			1	mA		
V <sub>CE</sub> = 1200 V	V <sub>CE</sub> = 1200 V			-		mA		
Cies	V <sub>CE</sub> = 25 V V <sub>GE</sub> = 0 V	f = 1 MHz		0.49		nF		
Coes		f = 1 MHz		0.05		nF		
C <sub>res</sub>		f = 1 MHz		0.03		nF		



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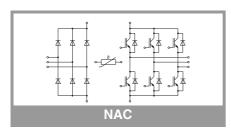
#### Features\*

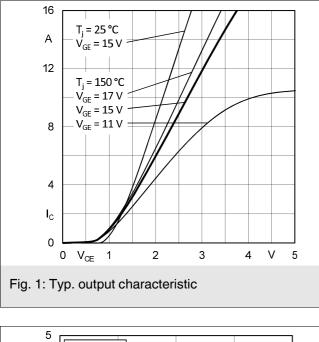
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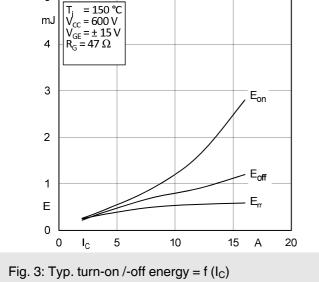
#### Remarks

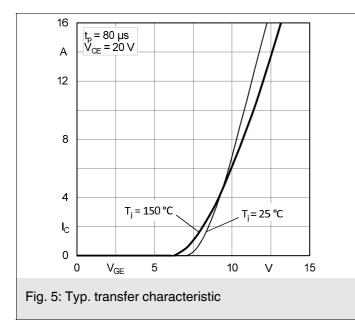
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- Product reliability results valid for  $T_j \le 150^{\circ}C$  (recommended  $T_{j,op} = -40...+150^{\circ}C$ )
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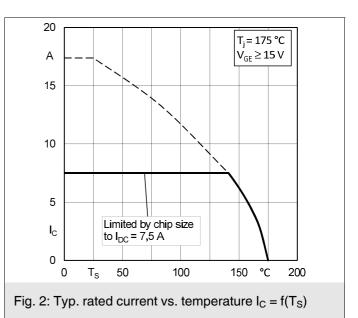
Characte	ristics					
Symbol	Conditions		min.	typ.	max.	Unit
Inverter -	IGBT					
Q <sub>G</sub>	V <sub>GE</sub> = - 8 V+ 15 \	/		45		nC
R <sub>Gint</sub>	T <sub>j</sub> = 25 °C			0		Ω
t <sub>d(on)</sub>	V <sub>CC</sub> = 600 V	T <sub>j</sub> = 150 °C		32		ns
t <sub>r</sub>	I <sub>C</sub> = 8 A	T <sub>j</sub> = 150 °C	34			ns
Eon	$R_{G on} = 47 \Omega$ $R_{G off} = 47 \Omega$	T <sub>j</sub> = 150 °C		0.9		mJ
t <sub>d(off)</sub>	$G_{\text{off}} = 47.52$	T <sub>j</sub> = 150 °C		295		ns
t <sub>f</sub>	ConditionsGBT $V_{GE} = -8 \ V+ 15 \ V$ $T_j = 25 \ ^{\circ}C$ $V_{CC} = 600 \ V$ $I_C = 8 \ A$ $R_{G \ on} = 47 \ \Omega$ $R_{G \ off} = 47 \ \Omega$ $V_{GE} = +15/-15 \ V$ per IGBT, $\lambda_{paste}=0.8$ Diode $I_F = 8 \ A$ $V_{GE} = 0 \ V$ chiplevelchiplevelchiplevellF = 8 \ A $V_{GE} = -15 \ V$ $V_{CC} = 600 \ V$ di/dt <sub>off</sub> = 335 \ A/\musper Diode, $\lambda_{paste}=0.8$ DiodeIF = 8 \ Achiplevel </td <td>T<sub>j</sub> = 150 °C</td> <td></td> <td>68</td> <td></td> <td>ns</td>	T <sub>j</sub> = 150 °C		68		ns
E <sub>off</sub>	V <sub>GE</sub> = +15/-15 V	T <sub>j</sub> = 150 °C		0.7		mJ
R <sub>th(j-s)</sub>	per IGBT, $\lambda_{paste}=0$ .	8 W/(K*m)		1.84		K/W
Inverse -	Diode					
$V_F = V_{EC}$		T <sub>j</sub> = 25 °C		2.33	2.65	V
	V <sub>GE</sub> = 0 V chiplevel chiplevel	T <sub>j</sub> = 150 °C		2.35	2.68	V
V <sub>F0</sub>	chiployol	T <sub>j</sub> = 25 °C		1.30	1.50	V
chiplevel	chipievei	T <sub>j</sub> = 150 °C		0.90	1.10	V
r <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		129	144	mΩ
	chipievei	T <sub>j</sub> = 150 °C		181	198	mΩ
I <sub>RRM</sub>	V <sub>GE</sub> = -15 V	T <sub>j</sub> = 150 °C		7.7		А
Q <sub>rr</sub>		T <sub>j</sub> = 150 °C		1.23		μC
Err		T <sub>j</sub> = 150 °C		0.5		mJ
R <sub>th(j-s)</sub>		per Diode, $\lambda_{\text{paste}}$ =0.8 W/(K*m) 2.53			K/W	
Rectifier -	Diode					
$V_F = V_{EC}$		T <sub>j</sub> = 25 °C		1.00	1.21	V
	chiplevel	T <sub>j</sub> = 125 °C		0.90	1.10	V
V <sub>F0</sub>	abiployal	T <sub>j</sub> = 25 °C		0.88	0.98	V
	chipievei	T <sub>j</sub> = 125 °C		0.73	0.83	V
۲ <sub>F</sub>	chiplevel	T <sub>j</sub> = 25 °C		15	29	mΩ
	-	T <sub>j</sub> = 125 °C		21	34	mΩ
R <sub>th(j-s)</sub>	per Diode, $\lambda_{paste}=0$	.8 W/(K*m)		1.5		K/W
Module						
Ms	to heat sink		2		2.5	Nm
w				20		g
Temperat	ure Sensor					
R <sub>100</sub>	$T_r = 100 \ ^{\circ}C$ , tolerance = 3 %			1670 ± 3%		Ω
R <sub>(T)</sub>	$\begin{array}{l} {\sf R}_{(T)}{=}1000\Omega[1{+}{\sf A}(T)] \\ {\sf A}=7.635^{*}10^{-3\circ}{\rm C} \\ {\sf B}=1.731^{*}10^{-5\circ}{\rm C}^{-2} \end{array}$	-25°C)+B(T-25°C) <sup>2</sup> ] - <sup>1</sup> °C <sup>-1</sup> , <sup>2</sup> °C <sup>-2</sup>				

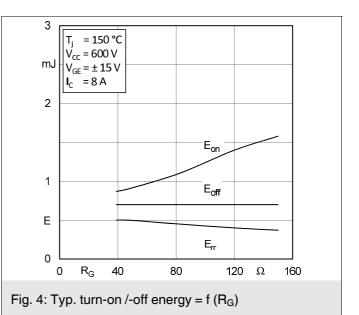


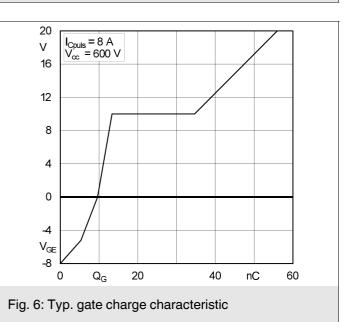




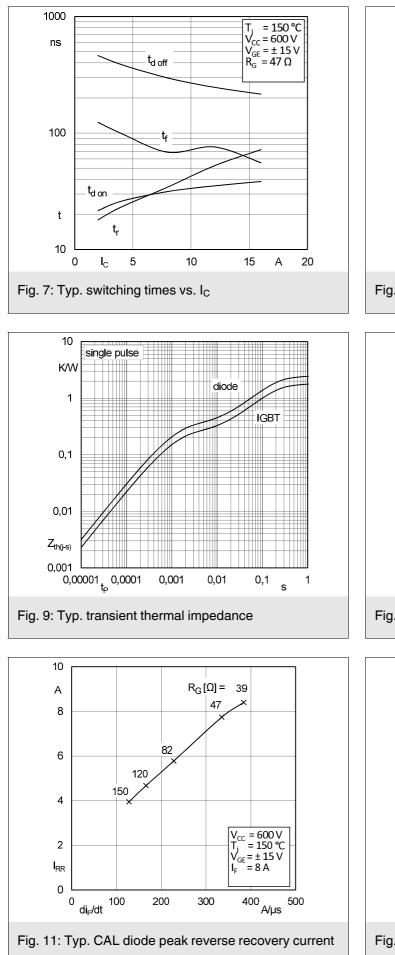


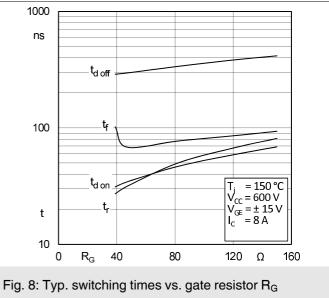


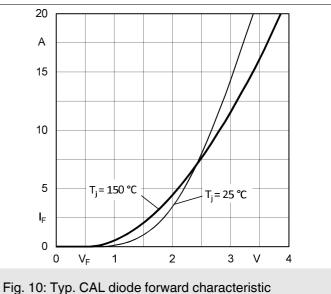


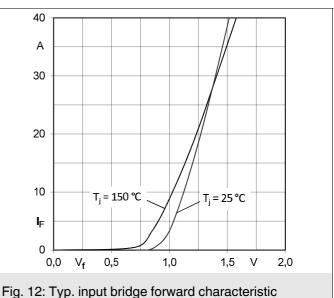


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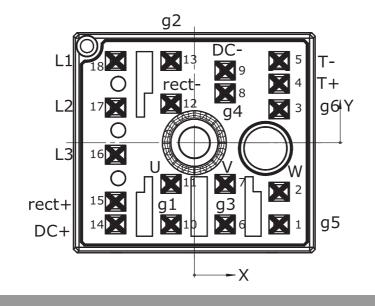




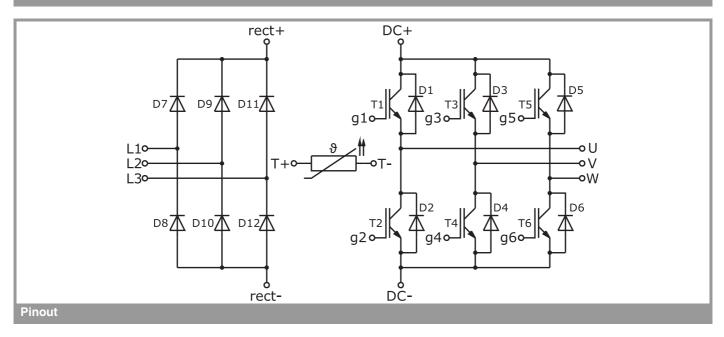
Rev. 5.0 - 21.09.2021

	Pin out						
Pin	X	Y	Function	Pin	X	Y	Function
1	11,93	-11,50	g5	10	-3,28	-11,50	g1
2	11,93	-6,90	W	11	-3,28	-5,80	U
3	11,93	4,71	g6	12	-3,28	5,50	rect-
4	11,93	8,3	T+	13	-3,28	11,50	g2
5	11,93	11,50	Т-	14	-11,08	-11,50	DC+
6	4,33	-11,50	g3	15	-11,08	-8,30	rect+
7	4,33	-5,80	V	16	-11,08	-1,68	L3
8	4,33	6,95	g4	17	-11,08	4,93	L2
9	4,33	10,15	DC-	18	-11,08	11,50	L1

all values in mm



**Pinout and Dimensions** 



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### **\*IMPORTANT INFORMATION AND WARNINGS**

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